APEMC
2016
Shenzhen, China

# 2016 ASIA-PACIFIC INTERNATIONAL SYMPOSIUM ON ELECTROMAGNETIC COMPATIBILITY &SIGNAL INTEGRITY

www.apemc.org

# Final Call for Papers

# 2016 Asia-Pacific International Symposium on Electromagnetic Compatibility & Signal Integrity and Technical Exhibition

## May 18-21, 2016,
## Shenzhen, China

The **7th（2016）Asia-Pacific International Symposium on Electromagnetic Compatibility & Signal Integrity and Technical Exhibition** (**APEMC2016**) will be held in Shenzhen, China, May 18 to 21, 2016. Shenzhen has been selected to host the 7th APEMC not only because of its strategic location next to Hong Kong, but also because of its fabulous facilities and world-class electronic industry and research centers.

This event will continue the APEMC spirit and address the world-wide EMC community with a primary focus on the Asia-Pacific region. The 7th APEMC will serve as a broad exchange platform for both academia and industry. The symposium will recognize innovations and technology leaderships through the Best Symposium Paper Award, the Best Student Paper Award, and other recognitions. The symposium will cover the entire scope of electromagnetic compatibility, electromagnetic environment, signal integrity issues and will feature EMC in emerging technologies. Prospective authors are invited to submit original papers on their latest research results. We also solicit proposals for focused sessions, industrial forums, workshops and tutorials.

## Important Dates

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| ■ Preliminary Paper Submission Deadline Extended to | **Dec. 21, 2015** |
| ■ ***Three (3)-page*** Preliminary Paper Submissions *(3-page papers presented at the conference will be included in the IEEE Digital Xplore with EI indexing)*<br>***OR***<br>■ ***One (1)-page*** Abstract Submission *(to be published in conference proceedings but NOT in IEEE Xplore; No final paper submissions are required)* | |
| ■ Notification of Acceptance | **Jan. 29, 2016** |
| ■ Final Paper Submission | **Mar. 9, 2016** |

*All submissions must be electronic. Details can be found in the symposium website:* ***www.apemc.org***

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## Symposium Topics

### ■ EMC Management and Standards
EMC Specifications & Standards; EMC Control and Management; Laboratory Accreditation; EMC Personnel Certification; National and Regional EMC Legislation; Mutual Recognition Agreements; EMC Education

### ■ EMC Measurements and Environment
Test Instrumentation; Time-Domain Measurements; Test Procedures; Emission and Immunity Testing; Test Facilities (reverberation and anechoic chambers etc), Confidence and Reproducibility; EM Environment

### ■ Lightning
Lightning Parameters and Models; Pulse Models; Coupling of Lightning EMF to Lines; Effects in the Atmosphere; Protection and Standards; Intentional EM Interference (IEMI)

### ■ High Power Electromagnetics
NEMP, HPM, EMP; High Power Protection; Intentional EM Interference (IEMI), High Voltage Power Grid EMC

### ■ Renewal Energy and Smart Power Grid EMC
Solar Cell System EMC, Wind Energy System EMC, Wireless Power Transmission; Power Delivery EMC; Power Electronics EMI

### ■ System-Level EMC and Protection
Electrically Large and Complex Systems including Transmission Lines; Shielding, Coupling and Grounding; EMC Product Design; EMC Topologies; System Installation Aspects; EMC Quality Assurance; EMC Cost Factors; Neural Networks and EMC; Visualization for EMC; Virtual EMC-Environment; PCB EMC

### ■ Automotive, Railway and Naval EMC
Automotive Components, Car Controllers; Radar Detection System EMC; Automotive System EMC; High Speed Rail EMC; High Speed EMC; Metropolitan Transit System EMC

### ■ EMC in Space
Space Electromagnetic Environment; Space Vehicles (Satellites, space crafts, space sensors, launch vehicles etc) EMC Issues; Avionics EMI

### ■ IC and Semiconductor EMC
ESD for Chips; Measurement of IC EMC; Modeling of IC EMC; EMC in System-on-Chip; EDA tools for IC EMC; RFIC EMC; RFID EMC; Smart Power IC EMC; Harsh EM Environment Effects on ICs

### ■ Signal Integrity and Power Integrity
Simulation Techniques; Measurement Techniques; Interconnects; Package Integration; PCB; System-in-Package; Chip-package and PCB Co-design and Simulation

### ■ Wireless Communication EMC
Cellular Devices & Systems; Internet Systems; Sub-station EMC; UWB, Wireless LAN EMC, Wireless Regulations

### ■ Computational Electromagnetics & Multiphyics
Numerical Techniques in EMC Problems; Fast Methods for Large/Complex Systems; Hybrid Methods; Validation and Benchmarking; Model Order Reduction Techniques; Advances in EM-based Electronic Design Automation Tools; Statistical Analysis

### ■ Bio-Medical EM
EM Interaction with Biological Systems at any Frequency; Exposure Studies; Medical Applications in Diagnosis and Therapy; Cellular Phone Dosimetry

### ■ Nanotechnology and Materials
Nanotube Interconnects; Nanomaterials for EMC; Metamaterials; PBG/EBG for EMI; Nanoelectronic EMC

### ■ Antenna and Propagation related to EMC

### ■ Topical-Symposiums
- ◆ **Wireless Power Transfer Technologies**
- ◆ **Smart Grid and Power Electronics EMC**
- ◆ **IC-EMC**

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## Paper Submission

***Authors have the options for 3-page paper or one-page abstract submissions.***

a) Authors can submit a ***3-page*** paper, including title, author's affiliation, abstract, figures and references. The presented papers will be included ***in the IEEEXplore with EI indexing***.

b) b) Authors can choose to submit ***one-page*** abstract including title, author's affiliation, key findings with max. 2 figures and 2-3 references. One-page abstract will be published in the conference proceedings, but NOT in the IEEEXplore.

The submission must be in electronic format (PDF). Word templates are available on the symposium website (**www.apemc.org**). No hardcopies will be accepted.

## Student Paper Prize

Papers considered for the Student Paper Prize are expected to be predominantly the work of the student. Papers co-authored by a student and his advisor are eligible, provided the student is the principal author and also the presenter. Please indicate in your electronic submission if you want to be considered for the Student Paper Prize.

## Accepted Papers

Notifications of paper acceptance and the necessary information to electronically submit the final version of the paper will be sent to the authors. Final papers shall be **three pages** in length, including figures, tables and references.

## Exhibition

The Technical Exhibition has always been a major highlight of the Asia-Pacific Symposium on Electromagnetic Compatibility (APEMC). The exhibition offers an excellent opportunity for all segments of the EMC and Microwave community to meet, providing an international gathering for everyone involved in technologies associated with RF, Microwave, EMC Instrumentation and analysis software, etc.

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